Specification of Thermoelectric Module

TEC1-02708S2CH4.0

Description

The 27 couples, 20mm x 20mm size module is a single stage module which is made of our high performance ingot to achieve superior cooling performance and 70°C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

Application

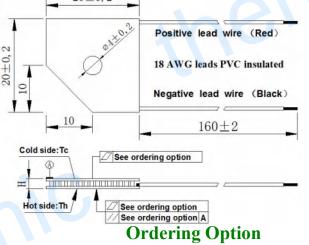
- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂	
DT _{max} (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U _{max} (Voltage)	3.4	3.7	Voltage applied to the module at DT _{max}	
I _{max} (Amps)	8.3	8.3	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	17.6	18.9	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (Ohms)	0.32	0.34	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters

Manufacturing Options



A. Solder:

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217°C)

2. SS: Silicone sealant

B. Sealant:

3. T240: SbSn (Tmelt = 240°C)

3. EPS: Epoxy sealant

C. Ceramics:

D. Ceramics Surface Options:

1. Alumina (Al $_2$ O $_3$, white 96%)

1. Blank ceramics (not metalized)

2. Aluminum Nitride (AlN)

2. Metalized

dering Option Naming for the Module

Suffix	Thickness	Flatness/	Lead wire length(mm)
Sullix	H (mm)	Parallelism (mm)	Standard/Optional length
TF	0:3.5± 0.1	0: 0.05/0.05	160±2/Specify
TF	$1:3.5 \pm 0.03$	1: 0.02/0.02	160±2/Specify

Eg. TF01: Thickness 3.5 ± 0.1 (mm) and Flatness 0.02/0.02 (mm)

Ceramic
Flatness/ Parallelisn
Sealant
Solder

CH4.0:Center hole diameter 4.0mm T100: BiSn (Tmelt=138°C)

AlO: Alumina (Al2O3, white 96%)

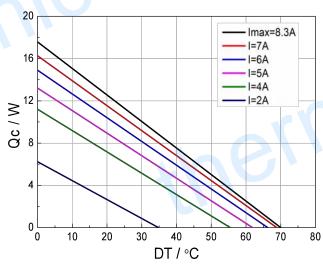
TF21: Thickness ±0.025(mm) and Flatness/ Parallelism 0.025/0.025 (mm)

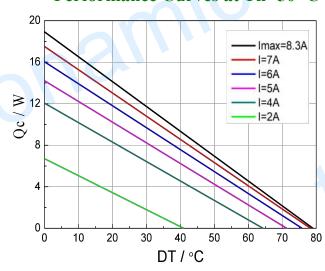
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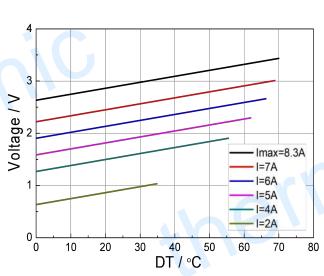
Performance Curves at Th=27 °C

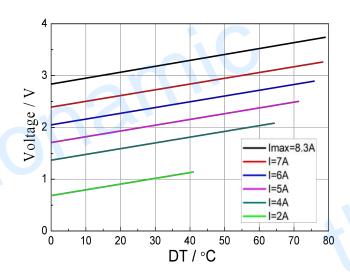
Performance Curves at Th=50 °C



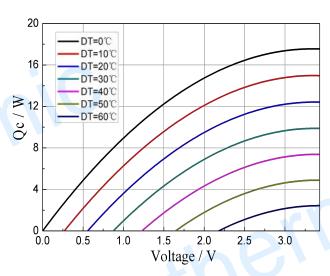


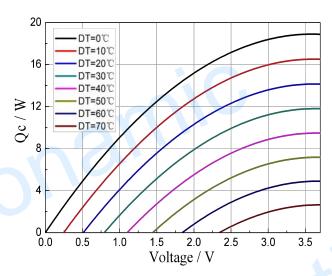
Standard Performance Graph Qc= f(DT)





Standard Performance Graph V= f(DT)





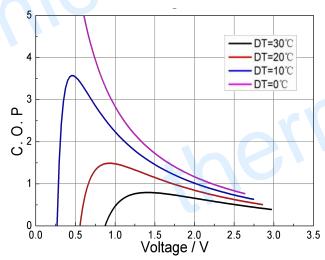
Standard Performance Graph Qc = f(V)

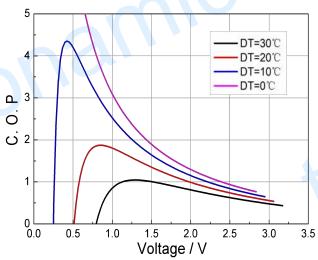
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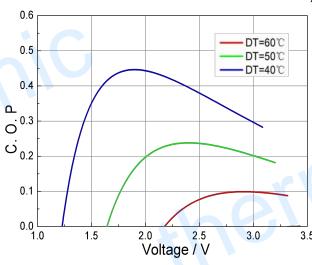
Performance Curves at Th=27 °C

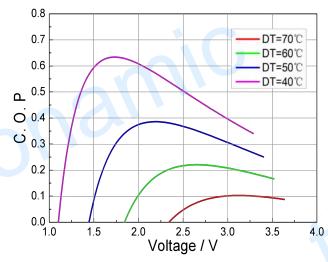
Performance Curves at Th=50 °C





Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power ($V \times I$).

Operation Caution

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.